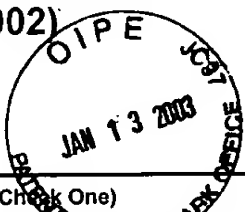


# FEE TRANSMITTAL SHEET (FOR FY 2002)



Complete if Known

Application No.	09/652,579
Filing Date	August 31, 2000
First Named Inventor	Vishnu K. Agarwal
Group Art Unit	2825
Examiner	Caridad M. Everhart
Atty. Docket Number	501082.14 (98-0616.13)

## METHOD OF PAYMENT (Check One)

1. ☒ The Commissioner is hereby authorized to charge any additional fee required under 37 C.F.R. §§ 1.16 and 1.17 and 1.136(a)(3) and credit any over payments to Deposit Account No.: 50-1266; Deposit Account Name: DORSEY & WHITNEY LLP

2. ☒ Check Enclosed

## FEE CALCULATION

### 1. BASIC FILING FEE

Large Entity		Small Entity		Fee Description
Fee Code	Fee (\$)	Fee Code	Fee (\$)	
101	750	201	375	<input type="checkbox"/> Utility Filing Fee
106	330	206	165	<input type="checkbox"/> Design Filing Fee
108	750	208	375	<input type="checkbox"/> Reissue Filing Fee
114	160	214	80	<input type="checkbox"/> Provisional Filing Fee

Subtotal (1) \$0

### 2. EXTRA CLAIM FEES

Current Claims	Prior	Extra	Fee	Fee Paid
Total	17	20	= 0 x \$	= \$0
Ind.	2	3	= 0 x \$	= \$0
Multiple Dependent Claims			x \$	= \$

Subtotal (2) \$0

Large Entity		Small Entity		Fee Description
Fee Code	Fee (\$)	Fee Code	Fee (\$)	
103	18	203	9	Claims in excess of 20
102	84	202	42	Independent claims in excess of 3
104	280	204	140	Multiple dependent Claim
109	84	209	42	Reissue independent claims over original patent
110	18	210	9	Reissue claims in excess of 20 and over original patent

## FEE CALCULATION (Continued)

### 3. ADDITIONAL FEES

Large Entity		Small Entity		Fee Description	Fee paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
105	130	205	65	Surcharge - Late filing fee or oath	\$
127	50	227	25	Surcharge - late provisional filing fee or cover sheet	\$
139	130	139	130	Non-English specification	\$
147	2,520	147	2,520	For Filing a Request for Reexamination	\$
195	300	196	300	Publication (early or Republication)	\$
115	110	215	55	Extension for reply within first month	\$
116	410	216	205	Extension for reply within 2 <sup>nd</sup> month	\$
117	930	217	465	Extension for reply within 3 <sup>rd</sup> month	\$
118	1,450	218	725	Extension for reply within 4 <sup>th</sup> month	\$
128	1,970	280	985	Extension for reply within 5 <sup>th</sup> month	\$
120	320	220	160	Filing a brief in support of an appeal	\$
121	280	270	140	Request for oral hearing	\$
148	110	248	55	Terminal Disclaimer Fee	\$
140	110	240	55	Petition to revive - unavoidable	\$
141	1,300	241	650	Petition to revive - unintentional	\$
142	1,300	242	650	Utility/Reissue issue fee (+ advance copies)	\$
143	470	243	235	Design issue fee (+ advance copies)	\$
122	130	122	130	Petitions to the Commissioner	\$
123	50	123	50	Petitions related to provisional applications	\$
126	180	126	180	Submission of IDS	\$180
581	40	81	40	Recording each patent assignment per property (times number of properties)	\$
179	750	279	375	Request for Continued Examination (RCE)	\$

Other fee (specify)

Subtotal (3) \$180

Total Amount of Payment: \$180

Submitted by:

Name: Paul F. Rusyn

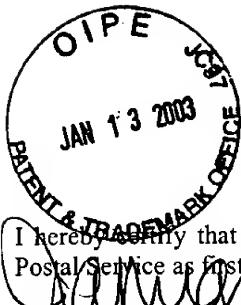
Reg. No.: 42,118

Telephone: (206) 903-8800

Signature:

Date:

8 January 2003



PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner of Patents, Washington, DC 20231.

Date

Ayesha S. Wilks

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Vishnu K. Agarwal

Attorney Docket No.: 501082.14 (98-0616.13)

Serial No. : 09/652,579

Group Art Unit : 2825

Filed : August 31, 2000

Examiner : Caridad M. Everhart

Title : DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A  
CONDUCTIVE LAYER IN SAID DEVICE

Commissioner of Patents  
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Claims:

Please cancel claims 47 and 48.

Please amend claims 76, 78, and 79 as follows:

76. (Amended) A method of treating a wafer, comprising:
- depositing a first conductive layer onto the wafer;
  - exposing the wafer in situ to a reducing environment;
  - depositing a second conductive layer; and
  - exposing the wafer to a material selected from the group consisting of phosphine, HCL, and boron trichloride.

2825  
#1610  
1/21/03

RECEIVED  
JAN 15 2003  
TECHNOLOGY CENTER 2800

C

C